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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : SCHREDL et al.  
Serial No :  
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For : CONTACT STRUCTURE FOR...  
Art Unit : 1772  
Examiner : SAVAGE, J.  
Dated : December 13, 2001

Hon. Commissioner of Patents  
and Trademarks  
Washington, D.C. 20231

INFORMATION DISCLOSURE STATEMENT

Applicant requests that the Examiner consider the following references which have come to Applicant's attention.

DE 41 09 363 A1 relates to the bonding of electrical or electronic components to wiring substrates using electro conductive adhesive for terminals and insulating adhesive for mounting. No translation of this reference is available to Applicant at this time. However, Applicant is attaching an English abstract.

U.S. 5,611,884 discloses a flip chip silicone pressure sensitive conductive adhesive.

U.S. 5,436,503 discloses a semi-conductor device and method of manufacturing the same.

DE 41 38 779 A1 discloses a procedure in which an integrated circuit is contacted on a flexible circuit board glass or ceramic substrate and the IC is fixed using organic resin which

contains highly conductive particles with irregular structure. No translation of this reference is available to Applicant at this time. However, a copy of an English language abstract is attached.

The publication "die elementaren Verbindungen: BGA und Flip-Chip" relates to chip fabrication and particularly wire bonding attachment and reflow. No translation of this reference is available to Applicant at this time. However, the captions of the drawings are in English.

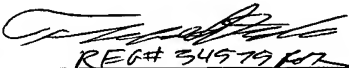
U.S. 5,400,950 discloses a method for controlling solder bump height for flip chip integrated circuit devices.

The publication "Lotkugeln auf Chip und Umhüllung" from the periodical Elektronik of January 1996 entitled Lotkugeln auf Chip und Umhüllung provides a discussion as to chip substrate connections. No translation of this reference is available to Applicant at this time.

The Patent Abstracts of Japan Publication No. 60067925 A of April 18, 1985 relates to a large size liquid crystal display device. A copy of the related Japanese patent document is also presented.

Consideration of the various references is requested.

Respectfully submitted  
for Applicant,

By:   
REG# 34579 P2  
John James McGlew  
Registration No. 31,903  
McGLEW AND TUTTLE, P.C.

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Enclosed: PTO-1449 Form

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SCARBOROUGH STATION  
SCARBOROUGH, NEW YORK 10510-0827  
(914) 941-5600

SHOULD ANY OTHER FEE BE REQUIRED, THE PATENT AND TRADEMARK OFFICE IS HEREBY REQUESTED TO CHARGE SUCH FEE TO OUR DEPOSIT ACCOUNT 13-0410.

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McGLEW AND TUTTLE, P.C.  
SCARBOROUGH STATION, SCARBOROUGH, NY 10510-0827

BY:  DATE: December 13, 2001